pSEMI MATERIAL DECLARATION FORM

Product:	**PE42451**
Ordering Codes:	**PE42451MLIAA, PE42451MLIAA-Z, EK42451-01**
Description:	**SP5T Absorptive UltraCMOS High-Isolation RF Switch 450-5000MHz Vss Option**
Package:	**24L 4X4 QFN**
Environmental Compliance	EU **RoHS** Directive 2011/65/EC and amendment 2015/863, **REACH** - EU ECHA SVHC, **Arsenic Free**, **JIG 101** - EIA/EICTA/JEITA, **Halogen Free** - IEC61249-2-21, **PFOS Free** - 2006/122/EC, **Antimony Trioxide Free**
Lead Finish	**NiPdAu**
Availability	**Now**

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Sapphire (Al2O3)	1344-28-1	2.027051	4.67%	46,650.88
Die	Silicon (Si)	7440-21-3	0.000673	0.00%	15.48
Die	Arsenic (As)	7440-38-2	0.000003	0.00%	0.08
Die	Boron (B)	7440-42-8	0.000001	0.00%	0.02
Die	Phosphorous (P)	7723-14-0	0.000226	0.00%	5.21
Die	Titanium (Ti)	7440-32-6	0.000078	0.00%	1.78
Die	Tungsten (W)	7440-33-7	0.000006	0.00%	0.14
Die	Copper (Cu)	7440-50-8	0.000010	0.00%	0.24
Die	Aluminum (Al)	7429-90-5	0.003375	0.01%	77.66
Die	Cobalt (Co)	7440-48-4	0.000000	0.00%	0.00
Leadframe	Copper (Cu)	7440-50-8	18.410900	42.37%	423,711.47
Leadframe	Iron (Fe)	7439-89-6	0.443700	1.02%	10,211.38
Leadframe	Zinc (Zn)	7440-66-6	0.022700	0.05%	522.42
Leadframe	Phosphorus (P)	7723-14-0	0.005700	0.01%	131.18
Die Attach	Silver (Ag)	7440-22-4	0.171200	0.39%	3,940.02
Die Attach	Epoxy Resin	9003-36-5	0.021400	0.05%	492.50
Die Attach	Diluent	26447-14-3	0.012800	0.03%	294.58
Die Attach	Dicyandiamide	461-58-5	0.002100	0.00%	48.33
Die Attach	Hardener	620-92-8	0.006400	0.01%	147.29
Gold Wire	Gold (Au)	7440-57-5	0.239400	0.55%	5,509.59
Internal Plating	Nickel (Ni)	7440-02-0	0.069000	0.16%	1,587.98
Internal Plating	Palladium (Pd)	7440-05-3	0.005600	0.01%	128.88
Internal Plating	Gold (Au)	7440-57-5	0.000200	0.00%	4.60
External Plating	Nickel (Ni)	7440-02-0	0.056700	0.13%	1,304.90
External Plating	Palladium (Pd)	7440-05-3	0.004600	0.01%	105.87
External Plating	Gold (Au)	7440-57-5	0.000180	0.00%	4.14
Mold Compound	Silica Fused	60676-86-0	20.125900	46.32%	463,180.76
Mold Compound	Epoxy Resin	Trade secret	0.877900	2.02%	20,204.13
Mold Compound	Phenol Resin	Trade secret	0.877900	2.02%	20,204.13
Mold Compound	Carbon Black	1333-86-4	0.065800	0.15%	1,514.33
Total Weight (mg)			**43.451503**	100.00%	1,000,000